



**INFORMATION DISCLOSURE
CITATION**

ATTY. DOCKET NO.

SERIAL NO.

925-287

10/809,681

APPLICANT

SHINGUBARA, S. et al.

FILING DATE

GROUP

March 26, 2004

1762

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (including Author, Title, Date, Pertinent pages, etc.)

KAB	Shingubara et al, "Effect of Pd Catalyst Adsorption on Cu Filling Characteristics in Electroless Plating", Advanced Metalization Conference, Conference Proceedings ULSI XVI, 2001, Materials Research Society, pp. 229-234
KAB	Wang et al, "Electroless Plating of Copper on Metal-Nitride Diffusion Barriers Initiated by Displacement Plating", Electrochemical and Solid-State Letters, 6 (3), 2003, pp. C38-C41
KAB	Wang et al, "Suppression of Native Oxide Growth in Sputtered TaN films and its Application to Cu Electroless Plating", Journal of Applied Physics, vol. 94, no. 7, 1 October 2003, pp. 4697-4701
KAB	Wang et al, "Influence of Surface Oxide of Sputtered TaN on Displacement Plating of Cu", Jpn. J. Appl. Phys., vol. 42, 2003, pp. 1843-1846
KAB	Wang et al, "Highly Adhesive Electroless Cu Layer Formation Using an Ultra Thin Ionized Cluster Beam (ICB)-Pd Catalytic Layer for Sub-100 nm Cu Interconnections, Jpn. J. Appl. Physics, vol. 42, 2003, pp. L1223-L-1225

*Examiner

/Katherine A. Bareford/

Date Considered

03/19/2007

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application.

Form PTO-FB-AB20 (Also PTO-1449)